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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10050013	01/17/2002	427		1762	

**APPLICANTS: Khaselev Oscar; Zavarine Igor; Zhang Yun;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		Khaselev 1-1-7
Verified and Acknowledged Examiners's initials		
TITLE : Electroplating solution for high speed plating of tin-copper solder		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg. Print Fig.
Amount Due		Application Examiner	
Date Paid			
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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